

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	266460	((chip\$2 die\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)near4 ((array\$2 plurality second multi\$6) (row \$2 and column\$2)))	US-PGPUB; USPAT	OR	ON	2008/04/27 19:37
L2	1226	(passage\$2 blind) near(via\$2 slit\$2 hole\$3 opening\$2) same (perforat\$4 semi\$1 cylind\$4)	US-PGPUB; USPAT	OR	ON	2008/04/27 19:39
L3	53	1 and 2	US-PGPUB; USPAT	OR	ON	2008/04/27 19:40
L4	46	((@ad<="20030227" @rlad<="20030227") and 3	US-PGPUB; USPAT	OR	ON	2008/04/27 19:41
L5	2693	((((chip\$2 die\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)near4 ((array\$2 plurality second multi\$6) (row \$2 and column\$2))) near7 (orthogonal\$4 perpendicul\$4 normal\$4 vertical\$4)).ti,clm,ab.	US-PGPUB; USPAT	OR	ON	2008/04/27 19:44
L6	76396	(passage\$2 blind) near(via\$2 slit\$2 hole\$3 openings\$2)	US-PGPUB; USPAT	OR	ON	2008/04/27 19:46
L7	39	5 and 6	US-PGPUB; USPAT	OR	ON	2008/04/27 19:46
L8	35	((@ad<="20030227" @rlad<="20030227") and 7	US-PGPUB; USPAT	OR	ON	2008/04/27 19:46
L9	13	((((chip\$2 die\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)near4 ((array\$2 plurality second multi\$6) (row \$2 and column\$2))) near7 (orthogonal\$4 perpendicul\$4 normal\$4 vertical\$4)).ti.	US-PGPUB; USPAT	OR	ON	2008/04/27 19:48
L10	49	("20030230802" "5421083")	US-PGPUB; USPAT	OR	ON	2008/04/27 19:49
L11	2	("20030230802" "5421083").pn.	US-PGPUB; USPAT	OR	ON	2008/04/27 19:50
L12	0	5 and 10	US-PGPUB; USPAT	OR	ON	2008/04/27 19:50
L13	241	((chip\$2 die\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)near4 (orthogonal\$4 perpendicul\$4 normal\$4 vertical\$4)).ti.	US-PGPUB; USPAT	OR	ON	2008/04/27 19:51
L14	187	((@ad<="20030227" @rlad<="20030227") and 13	US-PGPUB; USPAT	OR	ON	2008/04/27 19:52

L15	7	14 and 6	US-PGPUB; USPAT	OR	ON	2008/04/27 19:53
L16	5015	((chip\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)near4 (orthogonal \$4 perpendicul\$4 normal\$4 vertical\$4)) ti,clm,ab	US-PGPUB; USPAT	OR	ON	2008/04/27 19:54
L17	52	16 and 6	US-PGPUB; USPAT	OR	ON	2008/04/27 19:54
L18	40	((@ad<="20030227" @rlad<="20030227") and 17	US-PGPUB; USPAT	OR	ON	2008/04/27 19:54
L19	4677	257/E23.062 257/E25.013. ccls.	US-PGPUB; USPAT	OR	ON	2008/04/27 19:56
L20	238	16 and 19	US-PGPUB; USPAT	OR	ON	2008/04/27 19:57
L21	1	((perforat\$4 semi\$1 cylind\$4) and 20	US-PGPUB; USPAT	OR	ON	2008/04/27 19:57
L22	2216	((((prevent\$4 restrain\$4 reduc \$4 decreas\$4 eliminat\$4 suppress\$4)near7(wafer die chip real adj state)) ((improv\$ enhanc\$4 strength\$4 increas \$4)near5 (connection\$4 coupl \$5))) and 16	US-PGPUB; USPAT	OR	ON	2008/04/27 19:59
L23	171	22 and 19	US-PGPUB; USPAT	OR	ON	2008/04/27 19:59
L24	117	((@ad<="20030227" @rlad<="20030227") and 23	US-PGPUB; USPAT	OR	ON	2008/04/27 20:00
L25	7975	((chip\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)near4 (orthogonal \$4 perpendicul\$4 normal\$4 vertical\$4))	EPO; JPO; DERWENT	OR	ON	2008/04/27 20:02
L26	21	((perforat\$4 semi\$1 cylind\$4) and 25	EPO; JPO; DERWENT	OR	ON	2008/04/27 20:02
L27	563	257/E23.062 257/E25.013. ccls.	EPO; JPO; DERWENT	OR	ON	2008/04/27 20:03
L28	1	((perforat\$4 semi\$1 cylind\$4) and 27	EPO; JPO; DERWENT	OR	ON	2008/04/27 20:03
L29	169	((MICHAEL) near2 (BAUER)). INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:03
L30	26	((PETER) near2 (STROBEL)). INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:04
L31	30	((GERALD) near2 (ORNER)). INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:04
L32	1	((EDWARD) near2 (FURGUT)). INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:04
L33	24	((SIMON) near2 (JEREBO)). INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:04
L34	7	((THOMAS) near2 (BEMMERL)). INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:05

L35	4	((MARKUS) near2 (FINK)).INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:05
L36	14	((HERMANN) near2 (VILSMEIER)).INV.	US-PGPUB; USPAT	OR	OFF	2008/04/27 20:05
L37	1	(29 30 31 32 33 34 35 36) and 2	US-PGPUB; USPAT	OR	ON	2008/04/27 20:06
L38	138	(29 30 31 32 33 34 35 36) and (chip\$2 die\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)	US-PGPUB; USPAT	OR	ON	2008/04/27 20:07
L39	35	((@ad<="20030227" @rlad<="20030227") and 38	US-PGPUB; USPAT	OR	ON	2008/04/27 20:07
L40	248	((HERMANN) near2 (VILSMEIER)).INV. ((MARKUS) near2 (FINK)).INV. ((SIMON) near2 (JEREBOA)).INV. ((EDWARD) near2 (FURGUT)). INV. ((GERALD) near2 (ORNER)).INV. ((PETER) near2 (STROBEL)).INV. ((MICHAEL) near2 (BAUER)).INV.	EPO; JPO; DERWENT	OR	OFF	2008/04/27 20:11
L41	0	40 and 25	EPO; JPO; DERWENT	OR	ON	2008/04/27 20:11
L42	41	40 and (chip\$2 die\$2 ic integrated adj circuit\$2 semiconductor adj element\$2)	EPO; JPO; DERWENT	OR	ON	2008/04/27 20:12
L43	2126	257/620-621 257/501 257/513 257/520 257/522. ccls.	US-PGPUB; USPAT	OR	ON	2008/04/27 20:15
L44	1589	((@ad<="20030227" @rlad<="20030227") and 43	US-PGPUB; USPAT	OR	ON	2008/04/27 20:15
L45	406	257/620-621 257/501 257/513 257/520 257/522. ccls.	EPO; JPO	OR	ON	2008/04/27 20:16

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